Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 7508H Switch Chassis (JC789A)
HP A10508 Switch Chassis (JC612A)
HP 10508 TAA Switch Chassis (JG821A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		7
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove the left and right mounting angles 2 from the chassis.
2. Unscrew the screws on front panel 3 and then remove front front panel 3 from the chassis.
3. Unscrew the screws on blank panel 4, and then remove blank panel 4 from the chasssis.
4. Unscrew the screws on front panel 5, and then remove front panel 5 from the chassis.
5. Unscrew the screws on power cable channel sets 6, and then remove the power cable channel sets 6 from the chassis.
6. Unscrew the screws on part 7, and then remove part 7 from the chassis. The others should be removed in the same way.
7. Unscrew the screws on power module 8, and then remove power module 8 from the chassis.
8. Unscrew the screws on blank power module panel 9, and then remove blank power module panel 9 from the chassis.
9. Unscrew the screws on dust filter 10,11, and then remove the dust filter 10,11 from the chassis.
10. Remove the film 12 from the chassis.
11. Unscrew the screws on fan frame 13, and then remove fan frame 13 from the chassis.
12. Unscrew the screws on net board panel 14, and then remove net board panel 14 from the chasssi.
13. Unscrew the screws on net blank panel 16, and then remove net blank panel 16 from the chassis.
14. Unscrew the screws on flue panel A 15, and then remove the flue panel A 15 from the chassis.
15. Unscrew the screws on flue panel B 17, and then remove the flue panel B 17 from the chassis.
16. Unscrew the screws on flue panel C 18, and then remove the flue panel C 18 from the chassis.
17. Unscrew the screws on back cover 19, and then remove the back cover 19 from the chassis.
18. Unscrew the screws on back up rail 20, and then remove the back up rail 20 from the chassis.
19. Unscrew the screws on back down rail 21, and then remove the back down rail 21 from the chassis.
20. Remove all of the inner cables.
21. Unscrew the screws on PCB 22, and then remove PCB 22.
22. Unscrew the screws on strengthen plate 23, and then remove the strengthen plate 23.
23. Unscrew the screws on PCB 24, and then remove PCB 24.
24. Remove shielding finger 25 from the chassis.
25. Remove all of the labels and films.
26. Unscrew the screws on wire channel 2-2, and then remove wire channel 2-2 from mounting angle 2-1.
27. Unscrew the screws on pcb 3-2, and then remove pcb 3-3 from front panel 3-1.
28. Remove shielding finger 3-3 from front panel 3-1.
29. Remove film 3-4 from front panel 3-1.
30. Unscrew the screws on part 4-2, and then remove part 4-2 from front blank panel 4-1.
31. Remove shielding finger 4-3 from front blank panel 4-1.
32. Remove film 4-4 from front blank panel 4-1.
33. Unscrew the screws on part 5-2, and then remove part 5-2 from front panel 5-1.
34. Unscrew the screws on pcb 5-3, and then remove pcb 5-3 from front panel 5-1.
35. Remove shielding finger 5-4 from front panel 5-1.
36. Remove film 5-5 from front panel 5-1.
37. Unscrew the screws on power cable channel sets 6, and then remove the blocks 6-2 from wire road board 6-1
38. Unscrew the screws on part 13-1, and then remove the part 13-1 from fan frame 13.
39. Unscrew the screws on pcb 13-2, and then remove the pcb 13-2 from the part 13-3.
40. Unscrew the screws on part 13-3, Remove the fans 13-4.
41. Unscrew the screws on part 13-3,and then remove the handle 13-5 from the part13-3.
42. Remove the film 13-6 from the part 13-3.
43. Remove the EMIS 13-7 from the fan frame 13-3.
44. Unscrew the screws on pcb 14-2, and then remove pcb 14-2 from front panel 14-1.
45. Remove shielding finger 14-3 from front panel 14-1.

46. Remove film 14-4 from front panel 14-1.
47. Unscrew the screws on part 15-3, and then remove part 15-3 from flue panel B 15-1.
48. Remove shielding finger 15-2 from flue panel B 15-1.
49. Unscrew the screws on part 16-2, and then remove part1 16-2 from net blank panel16-1.
50. Remove shielding finger 16-3 from net blank panel 16-1.
51. Remove film 16-4 from net blank panel 16-1.
52. Unscrew the screws on part 17-2, and then remove part 17-2 from flue panel C 17-1.
53. Remove shielding finger 17-3 from flue panel C 17-1.
54. Unscrew the screws on part 18-2, and then remove part 18-2 from flue panel C 18-1.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

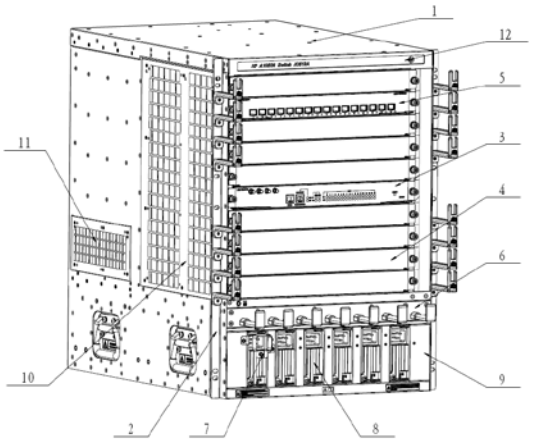

Figure 1 Treatments to the product (front view)

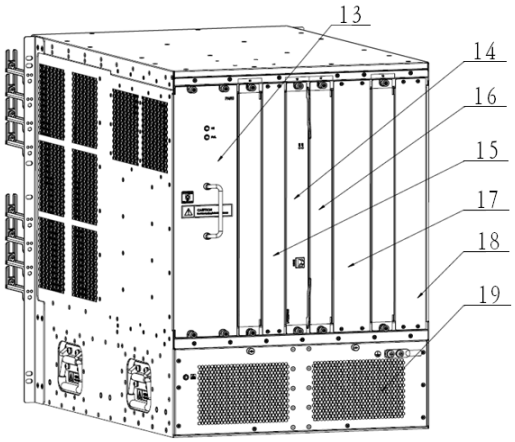

Figure 2 Treatments to the product (rear view)

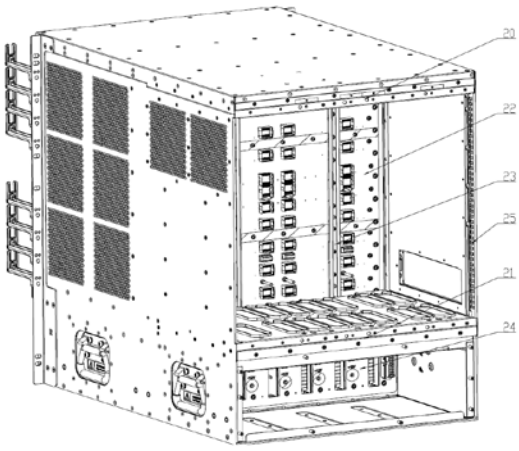

Figure 3 Treatments to the product (rear view)

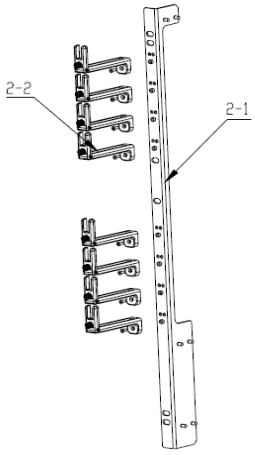

Figure 4 Treatments to mounting angle 2

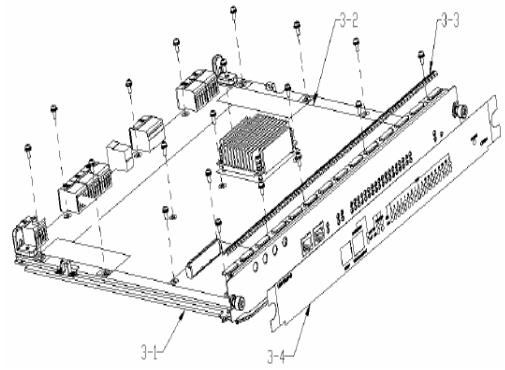

Figure 5 Treatments to front panel 3

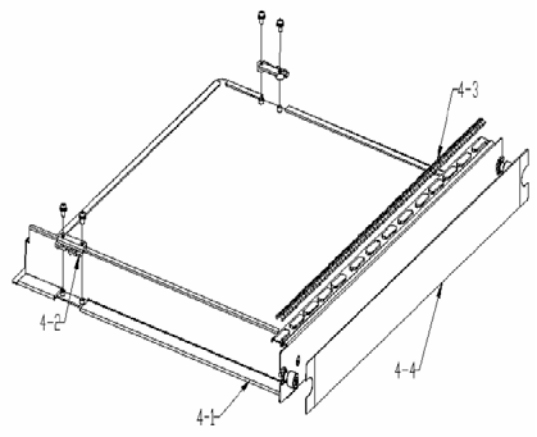

Figure 6 Treatments to front blank panel 4

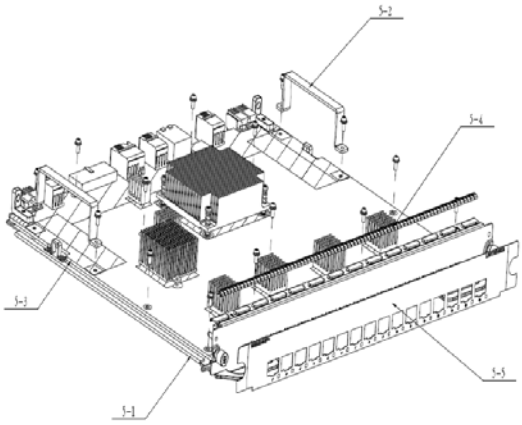

Figure 7 Treatments to front panel 5

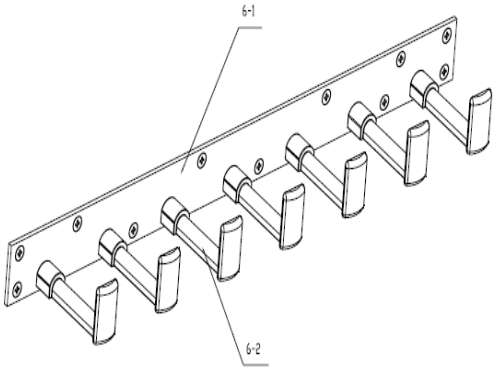

Figure 8 Treatments to upper wire channel sets 6

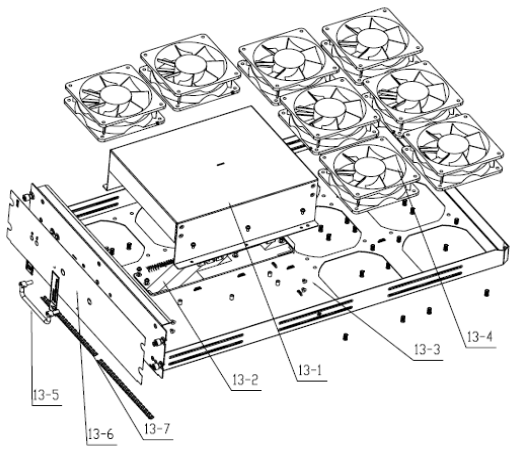

Figure 9 Treatments to fan frame 13

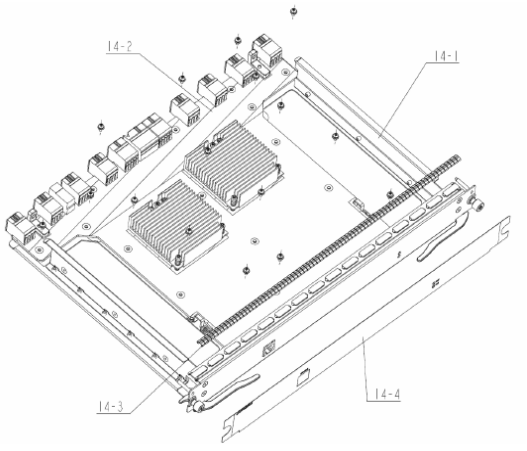

Figure 10 Treatments to net board panel 14

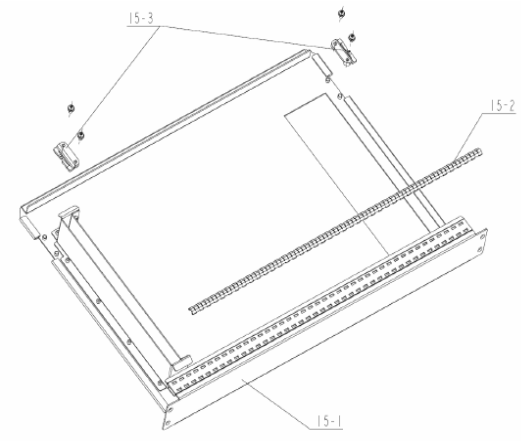

Figure 11 Treatments to flue panel A 15

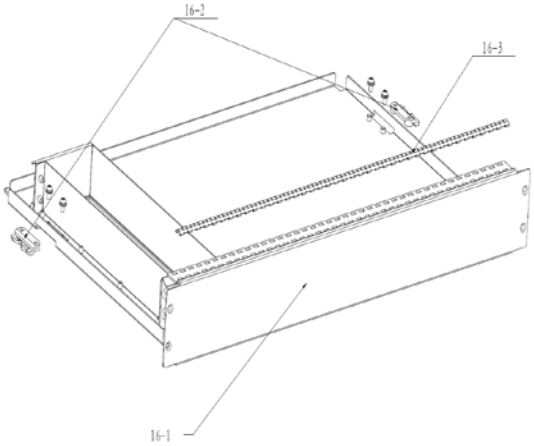

Figure 12 Treatments to net blank panel 16

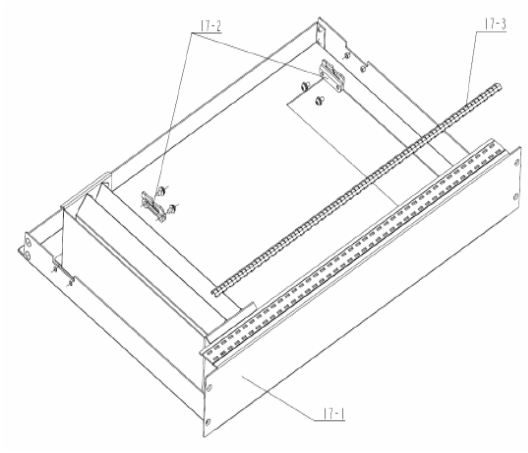

Figure 13 Treatments to flue panel B 17

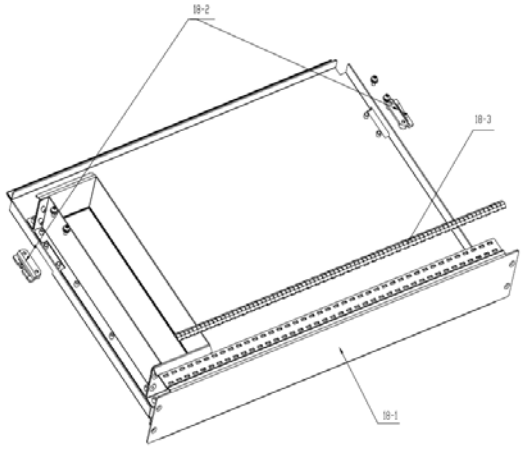

Figure 14 Treatments to flue panel D 18

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
	1	Fe	46944.189	54.95%		Fe recycling
2						
	2-1	Fe	182	0.21%		Fe recycling
	2-2	Al	30*16	0.56%		Al recycling

3						
	3-1	Fe	1520	1.78%		Fe recycling
	3-2	Complex PWB	1300	1.52%	The surface of PCB is greater than 10 square centimeters;	
	3-3	Be-Cu	4.3	0.01%		Cu recycling
	3-4	PC	2	0.00%	Containing brominated flame retardants	
4						
	4-1	Fe	1550	1.81%		Fe recycling
	4-2	PA	2	0.00%		Pla recycling
	4-3	Be-Cu	4.3	0.01%		Cu recycling
	4-4	PC	2	0.00%	Containing brominated flame retardants	
5						
	5-1	Fe	1520	1.78%		Fe recycling
	5-2	Fe	25*2	0.06%		Fe recycling
	5-3	Complex PWB	1900	2.22%	The surface of PCB is greater than 10 square centimeters;	

	5-4	Be-Cu	4.3	0.01%		Cu recycling
	5-5	PC	2	0.00%	Containing brominated flame retardants	
6						
	6-1	Fe	313.7	0.37%		Fe recycling
	6-2	Al	25.12*7	0.21%		Al recycling
	7	Fe	25	0.03%		Fe recycling
	8		2500	2.93%		
	9	Fe	130	0.15%		Fe recycling
	10	Fe	2090	2.45%		Fe recycling
	11	Fe	383	0.45%		Fe recycling
	12	PC	2.24	0.00%	Containing brominated flame retardants	
13						
	13-1	Fe	122.49	0.14%		Fe recycling
	13-2	Complex PWB	110	0.13%	The surface of PCB is greater than 10 square centimeters;	
	13-3	Fe	2433.7	2.85%		Fe recycling

	13-4		350*8	3.28%	Containing brominated flame retardants	
	13-5	Al	37	0.04%		Al recycling
	13-6	PC	9.98	0.01%	Containing brominated flame retardants	
	13-7	Be-Cu	4.5	0.01%		Cu recycling
14						
	14-1	Fe	1430	1.67%		Fe recycling
	14-2	Complex PWB	1100	1.29%	The surface of PCB is greater than 10 square centimeters;	
	14-3	Be-Cu	4.3	0.01%		Cu recycling
	14-4	PC	2	0.00%	Containing brominated flame retardants	
15						
	15-1	Fe	1460.5	1.71%		Fe recycling
	15-2	PA	2	0.00%		Pla recycling
	15-3	Be-Cu	4.3	0.01%		Cu recycling
16						
	16-1	Fe	1409.4	1.65%		Fe recycling

	16-2	PA	2	0.00%		Pla recycling
	16-3	Be-Cu	4.5	0.01%		Cu recycling
	16-4	PC	2	0.00%	Containing brominated flame retardants	
17						
	17-1	Fe	1873.7	2.19%		Fe recycling
	17-2	PA	2	0.00%		Pla recycling
	17-3	Be-Cu	4.5	0.01%		Cu recycling
18						
	18-1	Fe	2011.8	2.35%		Fe recycling
	18-2	PA	2	0.00%		Pla recycling
	18-3	Be-Cu	4.5*2	0.01%		Cu recycling
	19	Fe	775.79	0.91%		Fe recycling
	20	Fe	2078	2.43%		Fe recycling
	21	Fe	2404.8	2.81%		Fe recycling
	22	Complex PWB	2600	3.04%	The surface of PCB is greater than 10 square centimeters;	

	23	Fe	138.7*2	0.32%		Fe recycling
	24	Complex PWB	650	0.76%	The surface of PCB is greater than 10 square centimeters;	
	25	PC	0.65	0.00%		
Cables		Pla,Cu	710	0.83%	Containing brominated flame retardants	Pla & Cu recycling

4. Revised record

Date	Version	Author	Modify content
2012.04.17	V0	Xiao Dujun	Initial version
2013.10.14	V1	Chen Longjun	Add the module JG821A relation